

# Reliability Program and Design for Reliability Best Practices



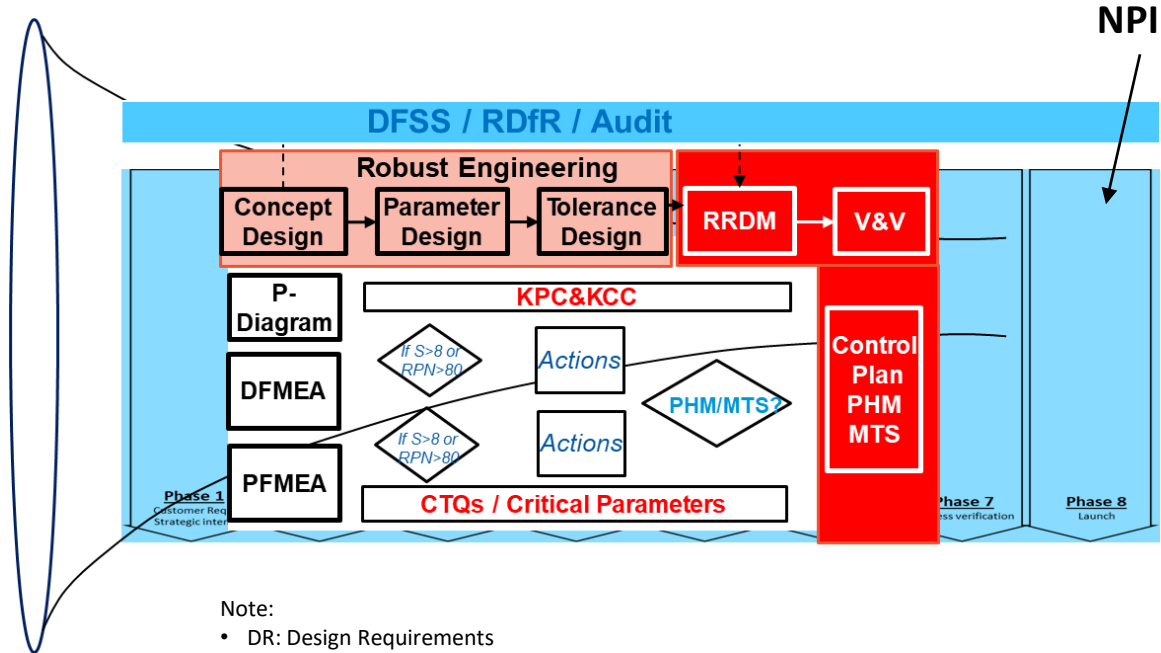
Reliability Activities in Concept Design

ASQ Reliability Forum

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# NPI/DfR/DFSS Alignment

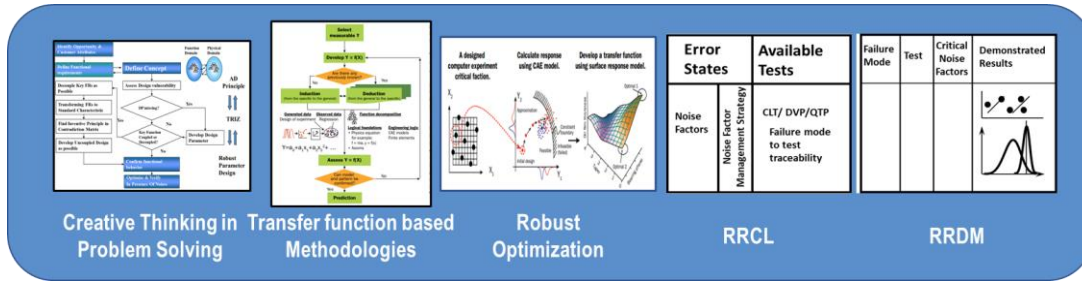
- DR
- UAE
- Warranty
- Die
- Components
- Interconnects
- Boards
- LRU
- Wiring
- Systems



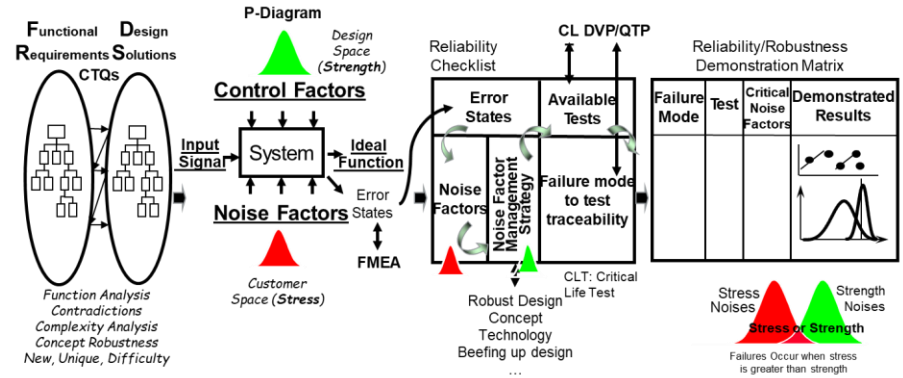
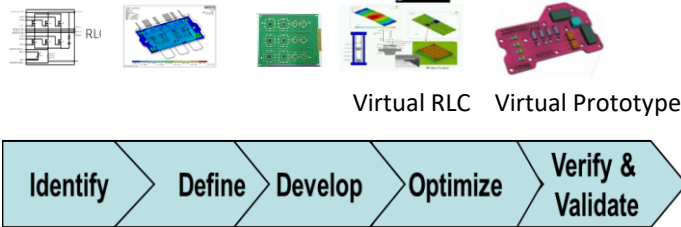
Note:

- DR: Design Requirements
- Uncontrollable Application Environment (UAE): N1 Mfg p-p variation, N2: Aging / deterioration, N3: Customer usage, N4: External Environment, N5: System/Subsystem/component interaction/interface
- RRDM: Reliability and Robustness Demonstration Matrix
- V&V: Verification and Validation
- LRU: Line Replaceable Units
- NPI: New Product Introduction

# Robust Design for Reliability Roadmap in Design Process

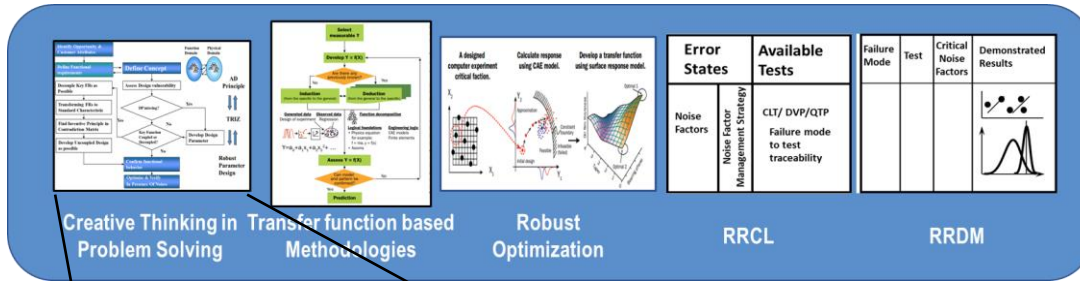


RRCL: Reliability & Robustness Checklist  
RRDM: Reliability & Robustness Demonstration

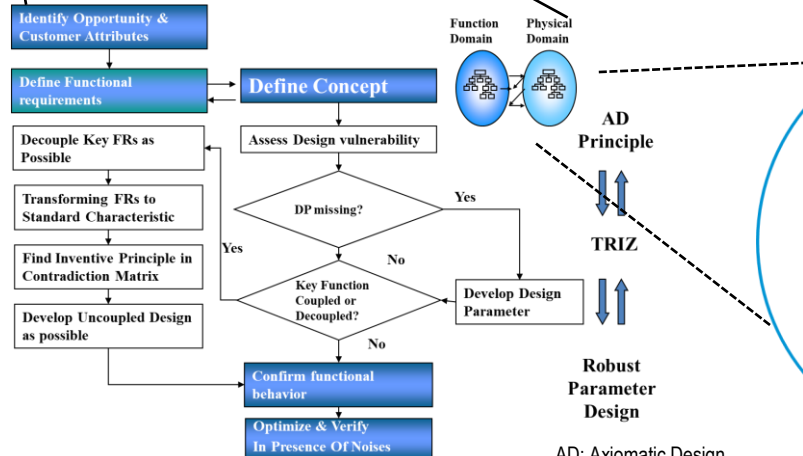


# Reliability in Concept Design Example:

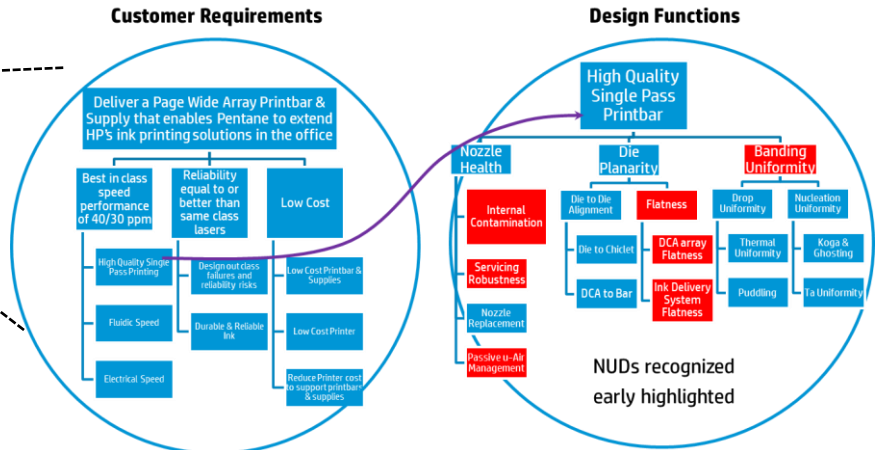
Use NUDs Classify Design Functions and Reliability Requirements



RRCL: Reliability & Robustness Checklist  
RRDM: Reliability & Robustness Demonstration



## Printer Concept Design Example:



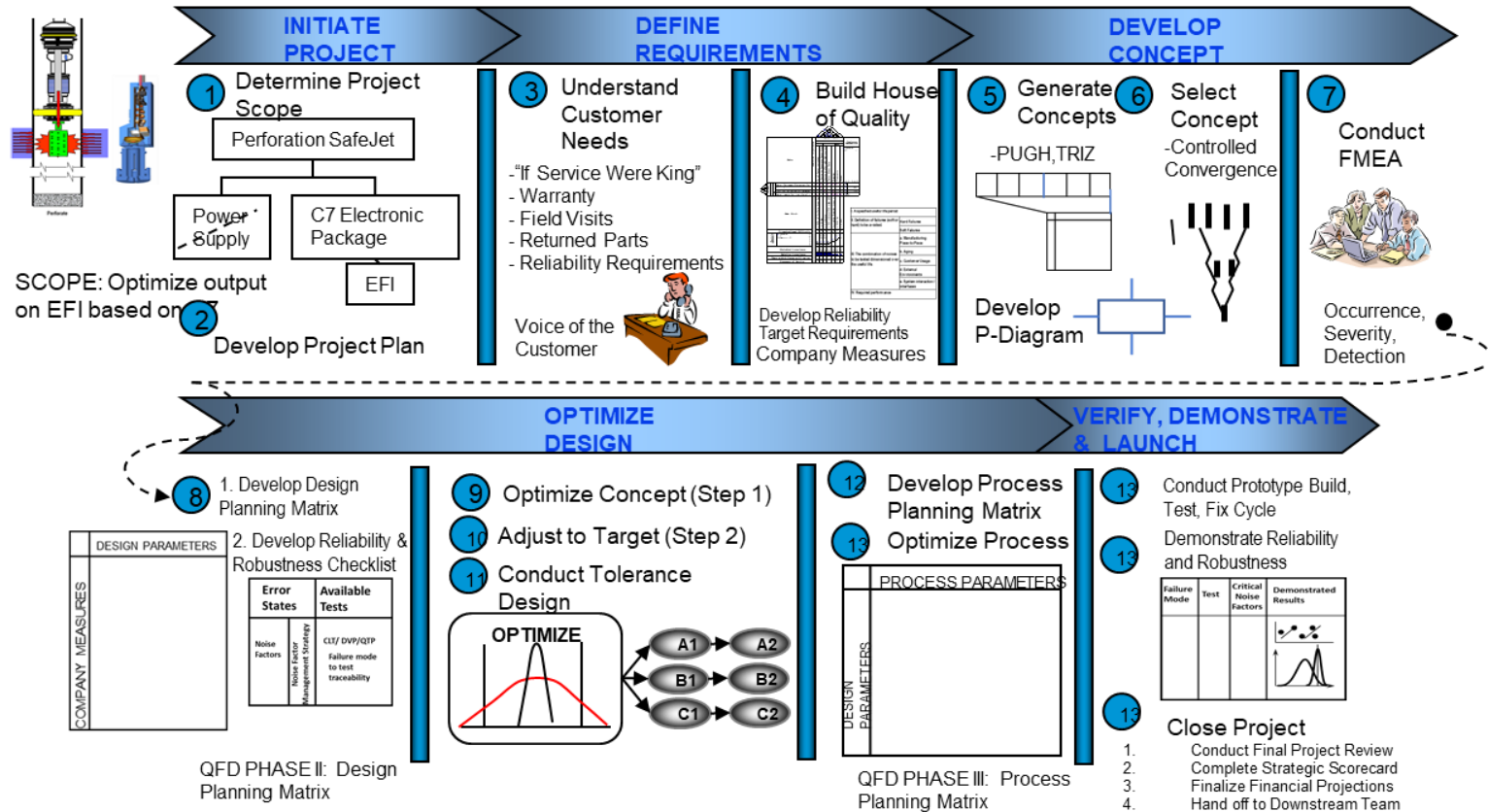
AD: Axiomatic Design  
TRIZ: The Theory of Inventive Problem Solving

NUD: New, Unique, Difficult



# Robust Design for Reliability (Combined with Design for Six Sigma)

Case Study: An application in Oil/Gas perforating explosive product development



# Case Study Report Summary (SafeJet Electronic Packaging RDfR)

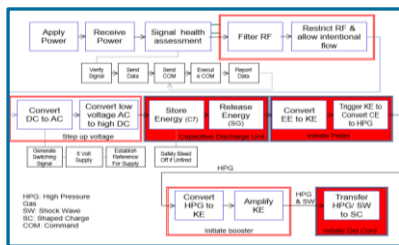
## SafeJet System Reliability Target Requirements

Useful life, Failure modes, Application condition, Expected performance

I. A specified useful life period (5 Years Shelf Life, or some other)	1 Year Shelf Life (date from manufactured / One-Shot/Code)
II. Definition of failures (soft or hard to be avoided)	Soft Failures 1. Mafire 2. Unlimited fire Hard Failures 1. Take too long to fire 2. Take too much voltage to fire 3. Diagnostic error
III. The combination of metrics to be tested/demonstrated over the useful life	Manufacturing Process: 1. Capacitor 2. Spark Gap 3. EFL 4. Noise 5. Resistance sub-assembly 6. SPC product assembly 7. Gun stop mechanism S-SPG 1. Storage in Binler 2. Shipping 3. Storage in assembled gun S-Capacitor usage 1. Storage in Binler S-SPG 1. Temperature 2. Humidity 3. Shock 4. Vibration 5. Chemical stress 6. Pressure 7. Radiation S-SPG 1. Temperature 2. Humidity 3. Shock 4. Vibration 5. Chemical stress 6. Pressure 7. Radiation S-SPG 1. Temperature 2. Humidity 3. Shock 4. Vibration 5. Chemical stress 6. Pressure 7. Radiation
IV. Required performance	1. The required probability that there is a 50-50% chance or greater that the Secure 2 will detonate within 3 seconds with input range of 200-300 psi without a misfire is at least 90% in the presence of combined noise factors. 2. The required performance is based on the Secure 1 current reliability performance of 87.2% up to 2000.



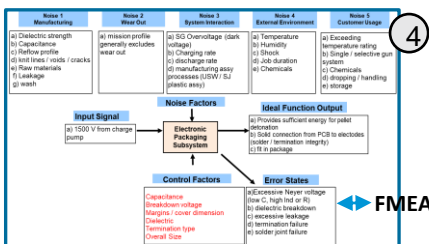
## Functional Diagram



## Function and Flow Analysis

SafeJet Functions and Flow				
Device/Form	Main Input Flow	Function	Main Output	
Charge Pump Unit	Switch	DC	Convert DC to AC	AC
Capacitor 7	Multiplier	AC	Convert low voltage AC to higher DC	DC
	Capacitor 7	DC	Store energy	DC
SG	DC	DC	Release energy	DC
Printed Circuit Board & Wire Assembly	Components / Subsystems	Holding all subsystems / components		PWA

## SafeJet C7 (Electronic Packaging P-Diagram)



FMEA

## SafeJet C7 Electronic Packaging RRCL (Reliability & Robustness Checklist)

Program / Subsystem	C7 Electronic Packaging	VERIFICATION METHODS
SRM1: FINISH TEST	1. Stores sufficient energy for pellet detonation	1. Visual Inspection
SRM2: FINISH TEST	2. Maintains connection from electrodes to PCB (solder / termination)	2. X-Ray Inspection
SRM3: FINISH TEST	3. Protects end fire in packaging	3. Visual Inspection
SRM4: FINISH TEST	4. Stores sufficient energy for pellet detonation	4. Visual Inspection
SRM5: FINISH TEST	5. Maintains connection from electrodes to PCB (solder / termination)	5. X-Ray Inspection
SRM6: FINISH TEST	6. Protects end fire in packaging	6. Visual Inspection
SRM7: FINISH TEST	7. Stores sufficient energy for pellet detonation	7. Visual Inspection
SRM8: FINISH TEST	8. Maintains connection from electrodes to PCB (solder / termination)	8. X-Ray Inspection
SRM9: FINISH TEST	9. Protects end fire in packaging	9. Visual Inspection
SRM10: FINISH TEST	10. Stores sufficient energy for pellet detonation	10. Visual Inspection
SRM11: FINISH TEST	11. Maintains connection from electrodes to PCB (solder / termination)	11. X-Ray Inspection
SRM12: FINISH TEST	12. Protects end fire in packaging	12. Visual Inspection
SRM13: FINISH TEST	13. Stores sufficient energy for pellet detonation	13. Visual Inspection
SRM14: FINISH TEST	14. Maintains connection from electrodes to PCB (solder / termination)	14. X-Ray Inspection
SRM15: FINISH TEST	15. Protects end fire in packaging	15. Visual Inspection
SRM16: FINISH TEST	16. Stores sufficient energy for pellet detonation	16. Visual Inspection
SRM17: FINISH TEST	17. Maintains connection from electrodes to PCB (solder / termination)	17. X-Ray Inspection
SRM18: FINISH TEST	18. Protects end fire in packaging	18. Visual Inspection
SRM19: FINISH TEST	19. Stores sufficient energy for pellet detonation	19. Visual Inspection
SRM20: FINISH TEST	20. Maintains connection from electrodes to PCB (solder / termination)	20. X-Ray Inspection
SRM21: FINISH TEST	21. Protects end fire in packaging	21. Visual Inspection
SRM22: FINISH TEST	22. Stores sufficient energy for pellet detonation	22. Visual Inspection
SRM23: FINISH TEST	23. Maintains connection from electrodes to PCB (solder / termination)	23. X-Ray Inspection
SRM24: FINISH TEST	24. Protects end fire in packaging	24. Visual Inspection

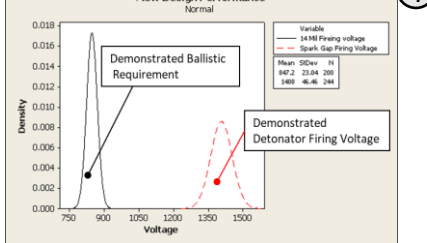
## SafeJet C7 Electronic Packaging Reliability & Robustness Demonstration Matrix

System	Assessed Component/Feature	Failure Mode	Test	Noise Factors	Reliability Requirement/Specs, Type, etc.	Test Target	Accelerated Test/Setup	Test Results	Issues
C7	Capacitor 7	Dielectric Breakdown	Visual Inspection	Excessive Neper voltage	Capacitance > 2.18 Cpk	100% Pass	100% Pass	100% Pass	None
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C7	Capacitor 7	Dielectric Breakdown	Visual Inspection	Excessive Neper voltage	Capacitance > 2.18 Cpk	100% Pass	100% Pass	100% Pass	None
C7	Capacitor 7	Dielectric Breakdown	Visual Inspection	Excessive Neper voltage	Capacitance > 2.18 Cpk	100% Pass	100% Pass	100% Pass	None
C7	Capacitor 7	Dielectric Breakdown	Visual Inspection	Excessive Neper voltage	Capacitance > 2.18 Cpk	100% Pass	100% Pass	100% Pass	None

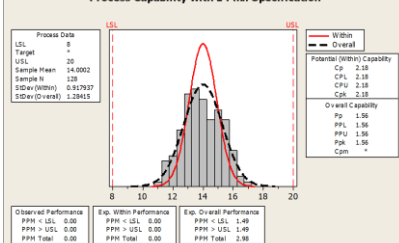
DRBTR

Design Review Based on Test Results

## New Design Performance



## Process Capability with 14 mJ Specification

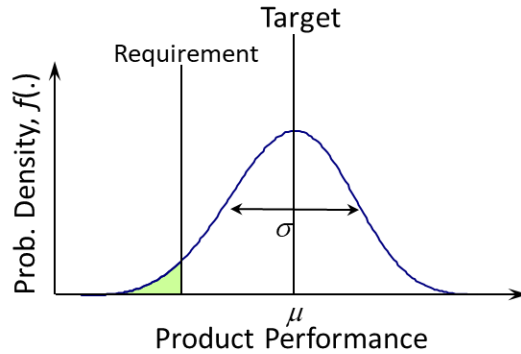


## Confirmed Results and Benefits

- Desensitized detonation reliability to the board manufacturing process.
- Enhanced data based decision-making based on robust barrel optimization study
- Improved and demonstrated 100% reliability & safety performance
- Achieved target performance and zero defect.
- Improved process capability from 0.24 Cpk to 2.18 Cpk
- Reduced \$340,000 manufacturing costs annually.

# Reliability and Robustness (An Engineering Measure of Reliability)

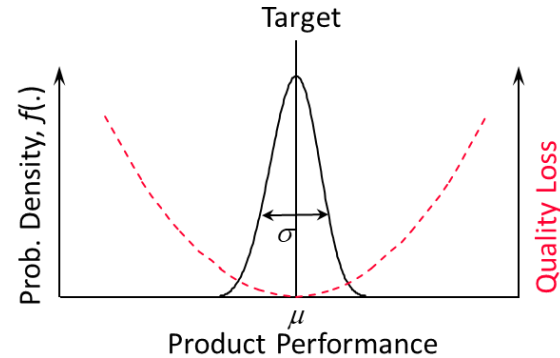
## (Robustness Solves the Problem)



**Reliability:** *probability* of a product performing its intended function for a specified life under the operating conditions encountered.

Q: How do you know the  $f(\cdot)$  when a design is new?

*Computing probability of success requires knowledge of  $m, s, f(\cdot)$*

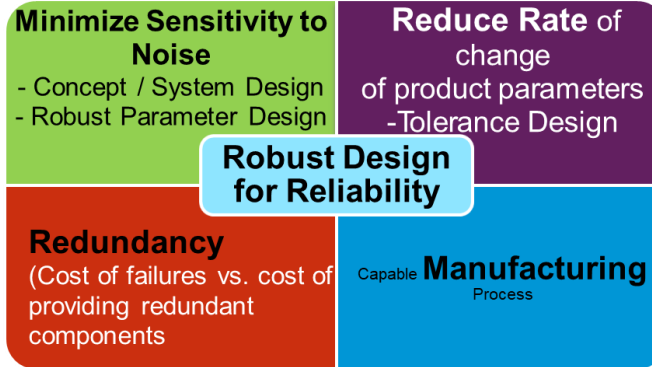
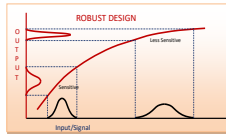
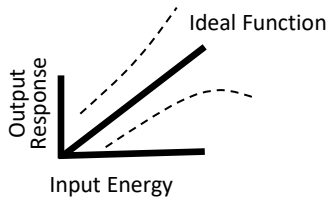


**Robustness:** ability of a product to perform its intended function consistently in the presence of uncontrollable user environment (noise) during its intended life. In other words, the product is insensitive to noise.

*Assessing robustness requires knowledge of  $m, s$*



# Summary



- Adopt the best practices including Robust Design for Reliability
- Start the reliability effort in early design phase
- Take advantage of virtual prototyping
- Electronics packaging reliability from die level to product level